ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES®	© Co	terial Compon pyright 2005. IPC, Bannock International and Pan-Americ	burn, Illinois	. All rights reserve	tion with lower	level p	arts, the	declaratior	n encon		ver level mate	erials for	which t	e item is an assembly he manufacturer has declaration.		
1752-2 1.1		Web Site for Information		-1752 Standa	rd					ration Class * 6 - RoHS Yes/No, Homogeneous Materials and Mfg Informat						
Supplier Information																
Company Name *		Company Unique ID		Unique ID Au	Ithority	Respo	Response Date *			Response Doo						
Semtech Corporation		SEMTECH CORPORATION			2016-1	2-05										
Contact Name *		Title - Contact		Phone - Con	Email - Contact *					0 1 1	A ()		1			
Elvia Finkel		Specialist, Document	Control/C	805-498-211 ⁻	efinkel@semtech.com				Duplicate	e Contact -	> Autho	orized Re	epresentative			
Authorized Representative * Titl		Title - Representative	•	Phone - Rep	Email - Representative *			*	Supplier Comr	nents or URL	for Add	ditional I	nformation			
Elvia Finkel		Specialist, Document	Control/C	805-498-211 ⁻	efinkel@semtech.com											
Requester Item Number		Mfr Item Number		Mfr Item Name	Effectiv	Effective Date Version			cturing Site	Weight *	UC	M	Unit Type			
		SX1278IMLTRT		Single chip 2	bands tranceiver			Mala		ia	0.09722	g		Each		
Alternate Recommend	ation				Alternate Item			Item Co	mments							
Manufacturing Proce	ss In	formation														
Terminal Plating / Grid Array	Mater	ial	Terminal Ba	ase Alloy	J-STD-020 MSL Ra	ating	Peak Proc	ess Body	Tempera	ature Max Time	e at Peak Temp	perature	Number	of Reflow Cycles		
Matte Tin (Sn) CU Alloy			3			260 C				30 se	conds	3				
SX1278IMLTRT is REAC	ЭН-со	mpliant product, per	EU Regu	lation EC190	7/2006 to include	recent	additior	n of SVH	C cand	idate list of s	ubstances ir	n June 2	2016			

Save the fields in this form to a file	Evport Data	Import fields from a file into this form	Import Data	Clear all of the fields on this form	Reset Form	Lock the fields on this form to prevent chan	Look Cupplier Fields
RoHS Materia	Composition Declar	ation				Declaration Type	* Detailed
		ty limit of 0.1% by mass (100 Ethers (PBDE) and quantity					ominated Biphenyls (PBB),
chromium, polybromina excess of an applicable gathered the information Company will rely on thi completing this form, ar certifications regarding conditions of that agree	ted biphenyls and/or polybrominate quantity limit, please indicate below it provides in this form using app s certification in determining the co d that Supplier may not have inde heir contributions to the part, and ment, including any warranty rights	ompliance of its products with European pendently verified such information. Ho those certifications are at least as comp	ricted substance?) in excess believe may apply. If the p y and that such information n Union member state laws owever, in situations where prehensive as the certificati hat agreement, will be the s	ss of the applicable quantity lim part is an assembly with lower I is true and correct to the best of that implement the RoHS Dire Supplier has not independently ion in this paragraph. If the Co sole and exclusive source of the	it identified above. If a homoge evel components, the declaration of its knowledge and belief, as of ctive. Company acknowledges y verified information provided lo popany and the Supplier enter is a Supplier?s liability and the Co	eneous material within the part cor on shall encompass all such comp of the date that Supplier complete: s that Supplier may have relied on by others, Supplier agrees that, at into a written agreement with resp impany?s remedies for issues that	ntains a RoHS restricted substance in ponents. Supplier certifies that it s this form. Supplier acknowledges that information provided by others in a minimum, its suppliers have provided
RoHS Declaration	n * 1 - Item(s) does not conta	ain RoHS restricted substances per the	he definition above			Supplier Acceptance *	Accepted
	e declared item does not co all applicable exemptions.	ntain RoHS restricted substanc	es per the definition a	above except for defined	RoHS exemptions, then	select the corresponding re	esponse in the RoHS Declaration
Declaration S	ignature						
In a family of the second	ward a factor and the factor of the second s	al Calaba and all manages of the last		a second se	• • • • •	and the second s	town - town

Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.

Supplier Digital Signature

Homogeneous Material Composition Declaration for Electronic Products

Subltem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Line Functions: +I Inserts a New Item /SubItem +M Inserts a new Material +C Inserts a new Substance Category +S Inserts a new Substance - Deletes the element line

	Item/SubItem		Homogeneous	Weight	Unit of			.evel	Substance Category			Substance	CAS	Exempt	Weight	Unit of	Tolerance		РРМ
	Name		Material	weight	Measure			evei	Substance Category			Substance	CAS	Exempt	weight	Measure	-	+	FFINI
+I -I	Die	+M -N	Silicon Chip	0.00205	g	+C -	C Su	upplier		+S	-S	Si	7440-21-3		0.00205	g		2	21,086
+1 -1	Lead Frame	+M -N	Ag Plated Cu C1	0.0375	g	+C -	-C Su	upplier		+S	-s	Cu	7440-50-8		0.03622	g		:	372,56
										+S	-s	Iron	7439-89-6		0.00085	g		;	8,701.9
						+C -	-C 🗚			+S	-s	Lead	7439-92-1		0.000001	g			11.57
						+C -	-C Su	upplier		+S	-s	Phosphorous	7723-14-0		0.000009	g			92.57
									•	+S	-S	Zinc	7440-66-6		0.000047	g			489.87
										+S	-S	Silver	7440-22-4		0.000375	g			3,857.2
+I -I	Die attach material	+M -N	Conductive epo	0.0007	g	+C -	C Su	upplier		+S	-s	Silver	7440-22-4		0.00056	g		į	5,796.1
										+S	-s	Carbocycllic Acrylate	Proprietary		0.00007	g			720.02
										+S	-s	Bismaleimide resin	Proprietary		0.000021	g		:	216
										+S	-s	2-preponoic acid, 2-met	68586-19-6		0.000021	g		:	216
										+S	-s	Additive	Proprietary		0.000021	g		:	216
										+S	-s	Dicumlyl peroxide	80-43-3		0.000004	g		;	36
+ -	Wire	+M -N	Gold	0.00063	g	+C -	-C Su	upplier		+S	-s	Au	7440-57-5		0.00063	g		f	6,479.5
						,,				+S	-s	Others	N/A		0.000000	g		1	0.65
+ -	Lead Finish	+M -N	Alloy	0.00035	g	+C -	-C Su	upplier		+S	-s	Sn	7440-31-5		0.000035	g		:	3,599.7
	3		_						•	+S	-S	Others	N/A		0.000000	g		-	0.36
+ -	Encapsulation	+M -N	EME-G770HC	0.05599	g	+C -	C Su	upplier		+S	-s	Silica Fused	60676-86-0		0.05246	g	· · · ·	;	539,62
<u> </u>										+S	-S	Epoxy Resin	Proprietary		0.00168	g		-	17,277
										+S	-S	Phenol Resin	Proprietary		0.00168	g		-	17,277
										+S	-S	Carbon Black	1333-86-4		0.00017	g			1,727.7